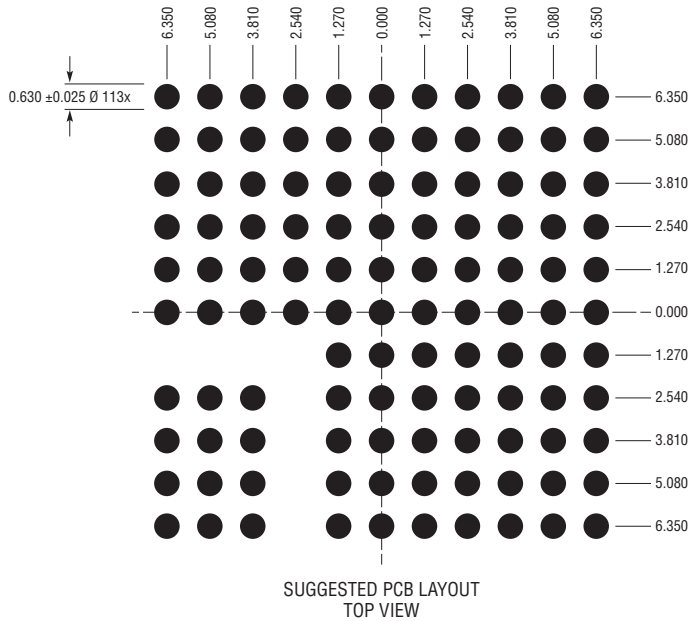
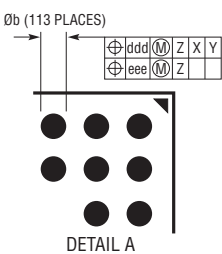
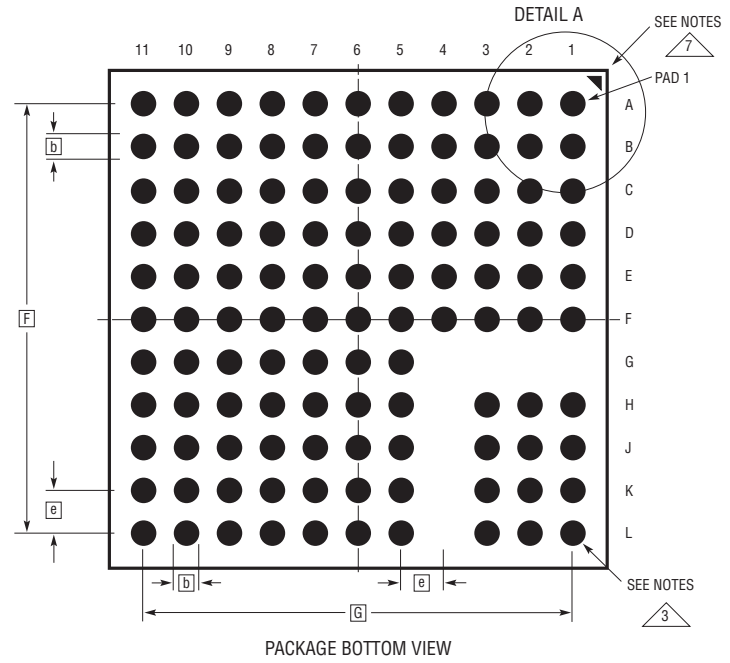
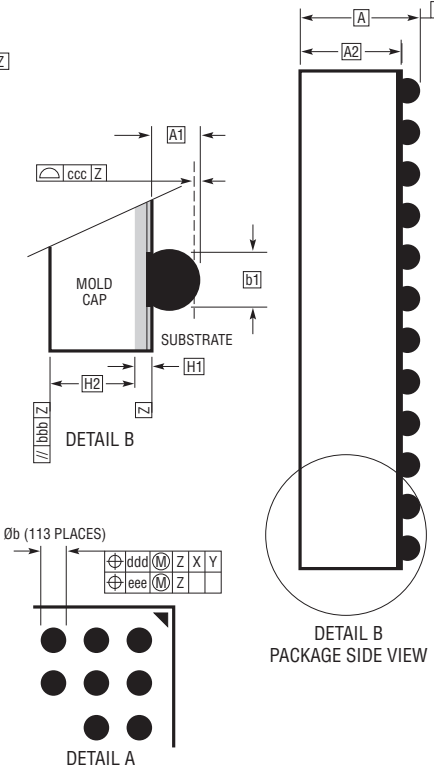
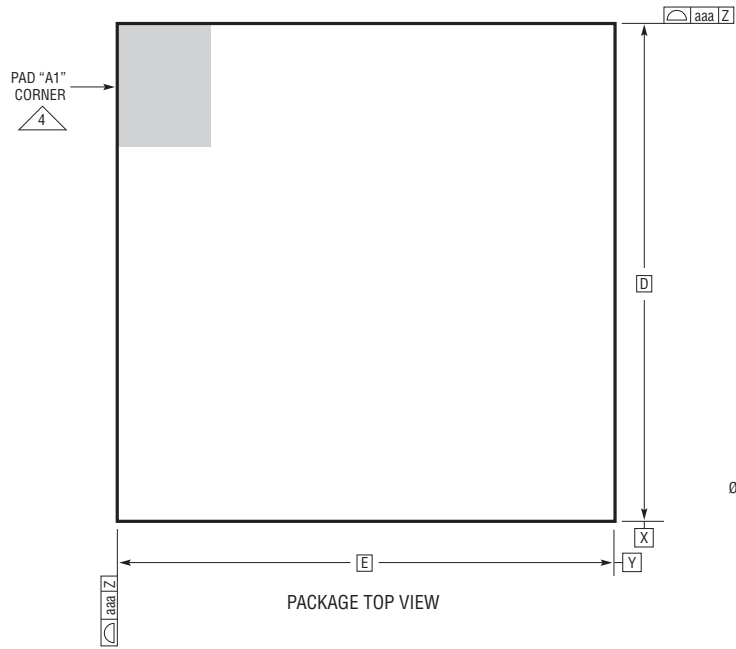


BGA Package
113-Lead (15mm × 15mm × 4.92mm)
 (Reference LTC DWG # 05-08-1980 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.72	4.92	5.12	
A1	0.50	0.60	0.70	
A2	4.22	4.32	4.42	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D	15.00			
E	15.00			
e	1.27			
F	12.70			
G	12.70			
H1	0.27	0.32	0.37	
H2	3.95	4.00	4.05	
aaa				0.15
bbb				0.10
ccc				0.20
ddd				0.30
eee				0.15
TOTAL NUMBER OF BALLS: 113				

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
 - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

